

SPECIFICATION

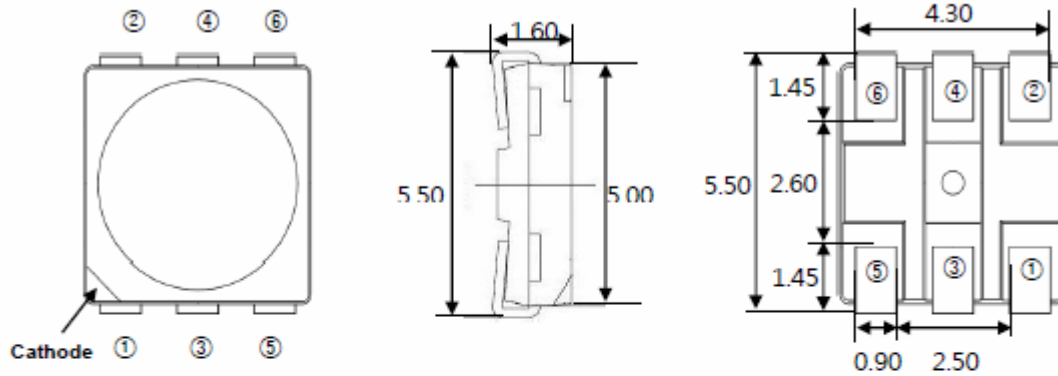
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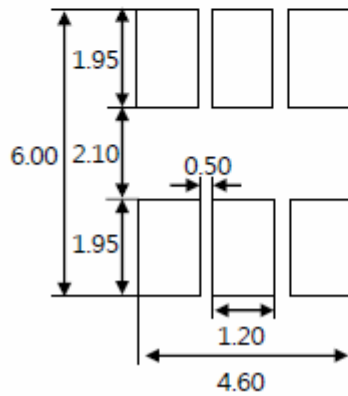


Outling Drawing :

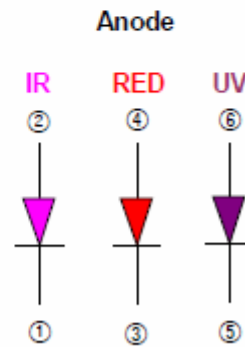
(unit : mm, Tolerance : ± 0.1 mm)



Recommended Soldering Pad Design



Circuit Diagram



- * The dimensional tolerance of the pin is ± 1.0 mm.
引腳的尺寸公差為 ± 1.0 mm
- * The width tolerance of the colloid is ± 0.05 mm.
膠體寬度公差為 ± 0.05 mm
- * The dimensional tolerance of the other is ± 0.2 mm.
其餘尺寸公差為 ± 0.2 mm

Material Information

材料成分表：

Feature & Applications

應用範圍：

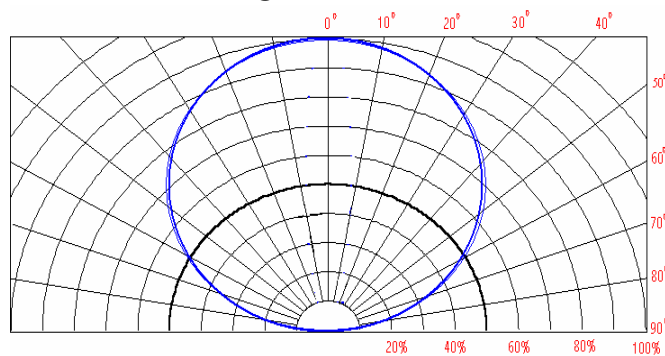
◆ Applications

- Package : SMD Top View Type
- Viewing Angle : $2\theta_{1/2} = 120^\circ$
- Colorless And Transparent Product
- InGaN Chip (UV), AlInGaP Chip (Red, IR)
- Long Time Reliability

◆ Applications

- Indoor/ Outdoor Lighting Equipment
- 室內及室外照明設備應用

Angel 角度圖：



Electro-optical Characteristic 光電特性表

T_J=25°C

Item 項目	Symbol 符號	Condition 條件	紅外光 (F)			紅光 (R)			紫光 (UV)			Unit 單位
			Min. 最小值	Typ. 平均值	Max. 最大值	Min. 最小值	Typ. 平均值	Max. 最大值	Min. 最小值	Typ. 平均值	Max. 最大值	
Forward Voltage 順向電壓	VF	IF=20mA	1.4	--	1.8	1.8	--	2.4	3.0	--	3.6	V
Reverse Current 反向電流	IR	VR=5v	--	--	10	--	--	10	--	--	10	μA
Viewing Angle 角度	2θ1/2	IF=20mA	--	120	--	--	120	--	--	120	--	deg
Luminous 光功率/ 光通量	mW/LM	IF=20mA	20mW	--	30mW	1LM	--	3LM	10mW	--	30mW	Lm
Forward Current 順向電流	IF	---	--	20	--	--	20	--	--	20	--	mA
Domain Wavelength 主波長	λ d	IF=20mA	845	--	855	620	--	630	400	--	410	nm

* ± 0.1V tolerance for the forward voltage may be caused by measurement inaccuracy.

正向電壓的測量公差為±0.1V

* The measurement tolerance of the domain wavelength is ± 2nm.

波長的測量公差為± 2nm

* Luminous flux measurement allowance is ±5%.

發光亮度的測量公差為±5%

* Viewing Angel measurement allowance is ±15%.

發光角度的測量公差為±15%

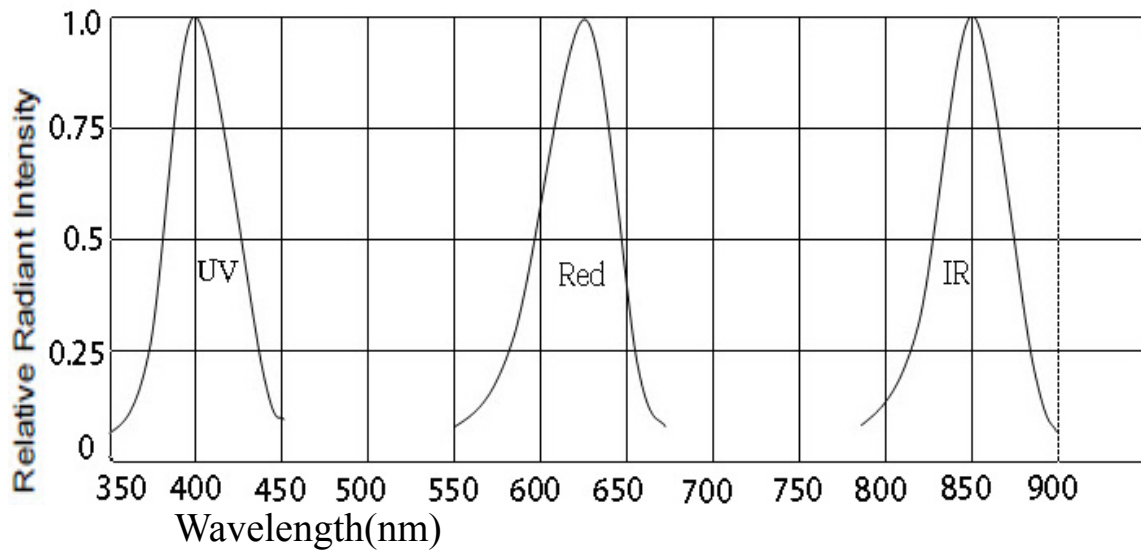
Absolute maximum Ratings 最大絕對額定值

Item 項目	Symbol 符號	額定值 (F)	額定值 (R)	額定值 (V)	Unit 單位
Pulse Current 脈衝電流	IFP	100	100	100	mA
Reverse Voltage 反向電壓	VR	5	5	5	V
Power 功率	PD	30	40	60	mW
Operating Temperature 工作溫度	TOPR	-20~+60	-20~+60	-20~+60	°C
Storage Temperature 儲存溫度	TSTG	-20~+60	-20~+60	-20~+60	°C
Soldering Temperature 無鉛焊接溫度	TSOL	Max. 260°C for 10sec. 260度不超過10秒			

* IFD Condition : Pulse current 10msec, Duty Ratio $\leq 1 / 10$.

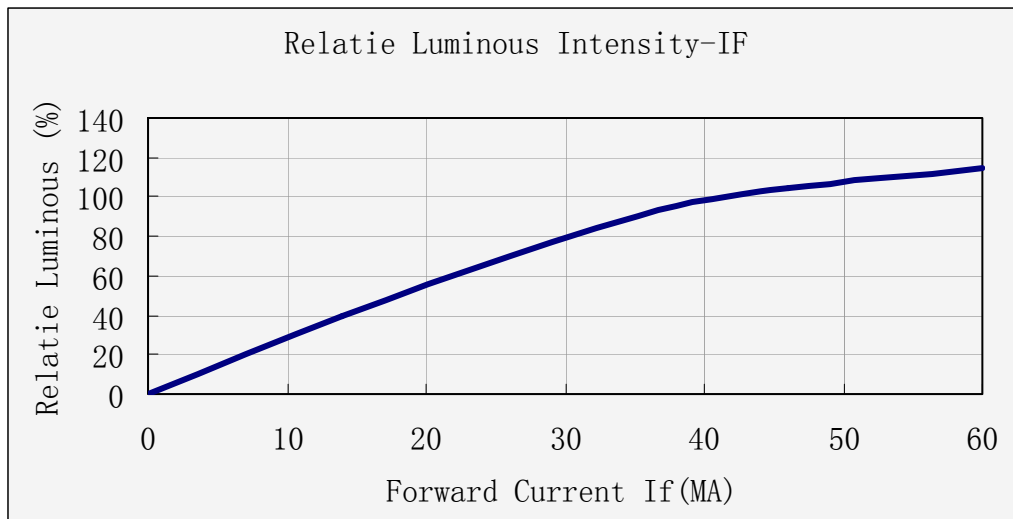
最大正向電流條件：脈衝寬度10msec，占空比 $\leq 1 / 10$ 。

Wavelength
波長特徵:



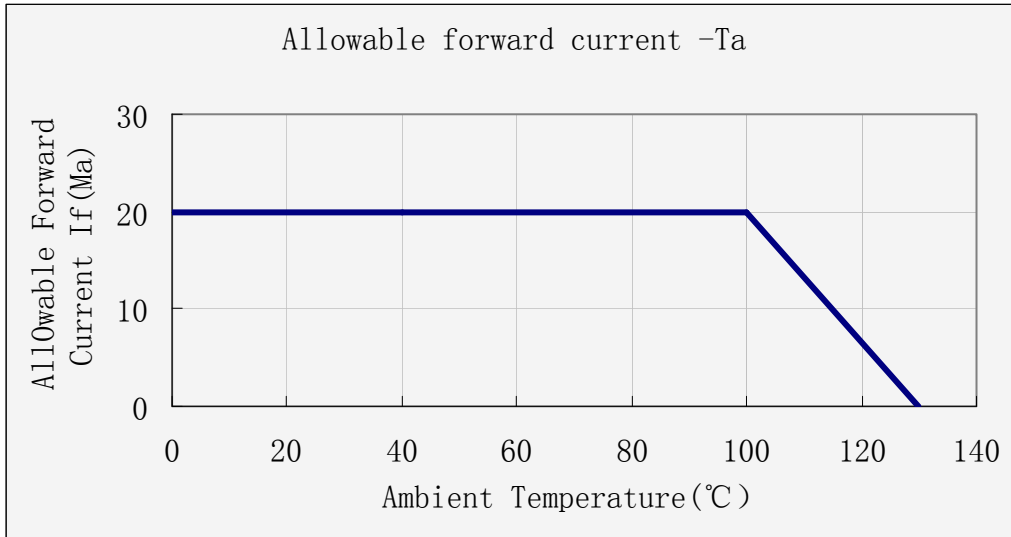
Relative Luminous and Forward Voltage

發光強度 vs.正向電流 :



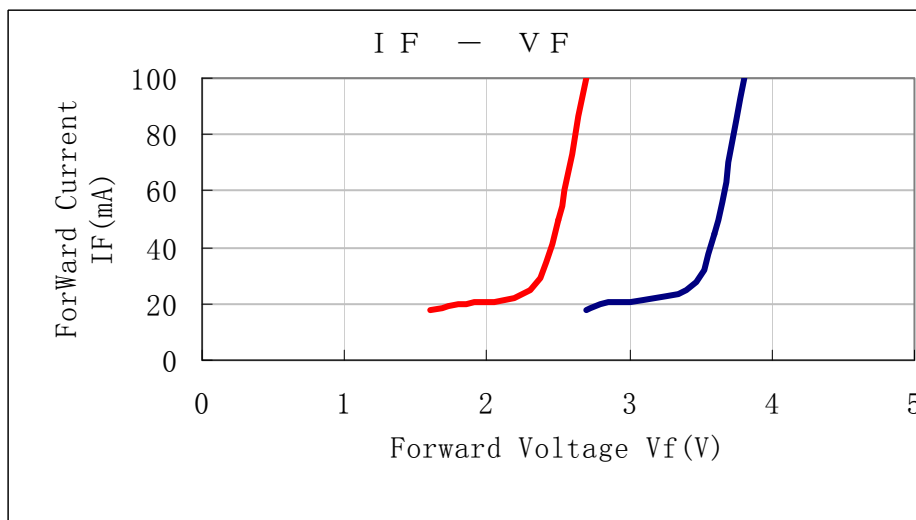
Allowable Forward Current and Temperature

正向電流 vs.溫度：



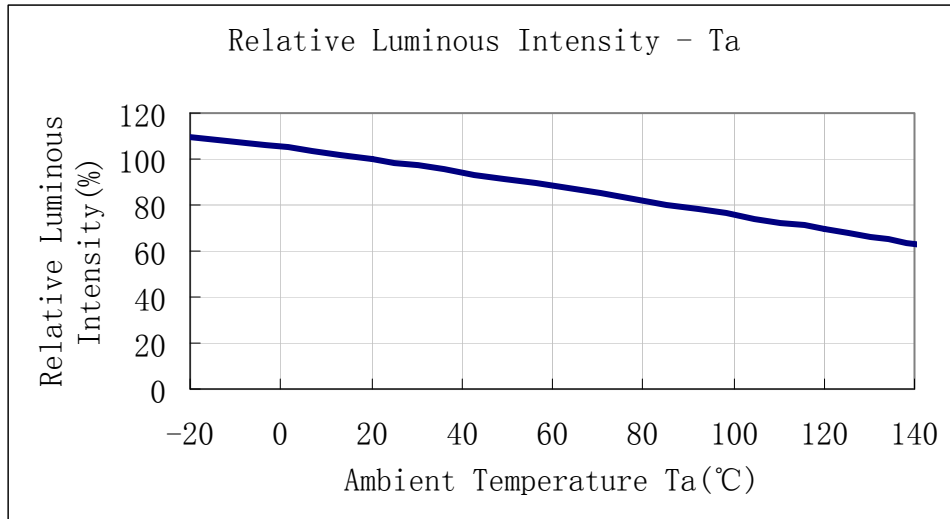
Forward Voltage and Current

順向電流 vs.電壓：



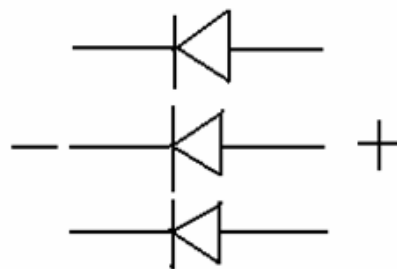
Relative Luminous Intensive and Temperature

發光強度 vs.溫度：



Chip Connection

晶片連接方式：



Precaution For Use 注意事項：

1) Storage

In order to avoid the absorption of moisture, it is recommended to store in a dry box (or a desiccator) with a desiccant. Otherwise, to store them in the following environment is recommended.

Temperature : 5°C ~ 30°C Humidity : maxim 65%RH

為了避免受潮，建議將產品儲存備有乾燥劑的防潮箱內。或是可將產品存放在溫度5-30°C，溼度不超過65%的環境中。

2) Attention after open.

After opened and mounted the soldering shall be using within 24 hours.

產品拆開密封包裝後必須在24小時內使用完

Temperature : 5 ~ 40°C Humidity : less than 30%

3) It is recommended that user should complete the use of the whole package within 48 hours upon unsealing. In the event of incomplete usage, It is advised that user preheat the remaining devices at 60±5°C for 10-12hours prior to use.

建議開封後的產品要在48小時內使用完畢，若未使用完畢，建議下次要使用之前先以60±5°C烘烤10-12小時。

Soldering Conditions

焊接条件

Item 項目	Temperature 溫度	Time 時間	Power 功率
Soldering 焊接	≤310°C	≤2sec	≤25W

Reflow Conditions

回流焊設定參考：

一温区	二温区	三温区	四温区	五温区	六温区	七温区	八温区
130°C /45S	150°C /45S	170°C /45S	190°C /45S	220°C /45S	235°C /45S	180°C /45S	150°C /45S

